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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2006
Number of Logic Elements/Cells	20060
Total RAM Bits	294912
Number of I/O	301
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	400-BGA
Supplier Device Package	400-FBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1c20f400c7

Table 1–1. Cyclone Device Features (Part 2 of 2)

Feature	EP1C3	EP1C4	EP1C6	EP1C12	EP1C20
Total RAM bits	59,904	78,336	92,160	239,616	294,912
PLLs	1	2	2	2	2
Maximum user I/O pins *(1)*	104	301	185	249	301

Note to Table 1–1:
(1) This parameter includes global clock pins.

Cyclone devices are available in quad flat pack (QFP) and space-saving FineLine® BGA packages (see Tables 1–2 through 1–3).

Table 1–2. Cyclone Package Options and I/O Pin Counts

Device	100-Pin TQFP *(1)*	144-Pin TQFP *(1), (2)*	240-Pin PQFP *(1)*	256-Pin FineLine BGA	324-Pin FineLine BGA	400-Pin FineLine BGA
EP1C3	65	104	—	—	—	—
EP1C4	—	—	—	—	249	301
EP1C6	—	98	185	185	—	—
EP1C12	—	—	173	185	249	—
EP1C20	—	—	—	—	233	301

Notes to Table 1–2:
(1) TQFP: thin quad flat pack.
PQFP: plastic quad flat pack.
(2) Cyclone devices support vertical migration within the same package (i.e., designers can migrate between the EP1C3 device in the 144-pin TQFP package and the EP1C6 device in the same package).

Vertical migration means you can migrate a design from one device to another that has the same dedicated pins, JTAG pins, and power pins, and are subsets or supersets for a given package across device densities. The largest density in any package has the highest number of power pins; you must use the layout for the largest planned density in a package to provide the necessary power pins for migration.

For I/O pin migration across densities, cross-reference the available I/O pins using the device pin-outs for all planned densities of a given package type to identify which I/O pins can be migrated. The Quartus® II software can automatically cross-reference and place all pins for you when given a device migration list. If one device has power or ground pins, but these same pins are user I/O on a different device that is in the migration path,the Quartus II software ensures the pins are not used as user I/O in the Quartus II software. Ensure that these pins are connected

to the appropriate plane on the board. The Quartus II software reserves I/O pins as power pins as necessary for layout with the larger densities in the same package having more power pins.

Table 1–3. Cyclone QFP and FineLine BGA Package Sizes

Dimension	100-Pin TQFP	144-Pin TQFP	240-Pin PQFP	256-Pin FineLine BGA	324-Pin FineLine BGA	400-Pin FineLine BGA
Pitch (mm)	0.5	0.5	0.5	1.0	1.0	1.0
Area (mm^2)	256	484	1,024	289	361	441
Length × width (mm × mm)	16×16	22×22	34.6×34.6	17×17	19×19	21×21

Document Revision History

Table 1–4 shows the revision history for this document.

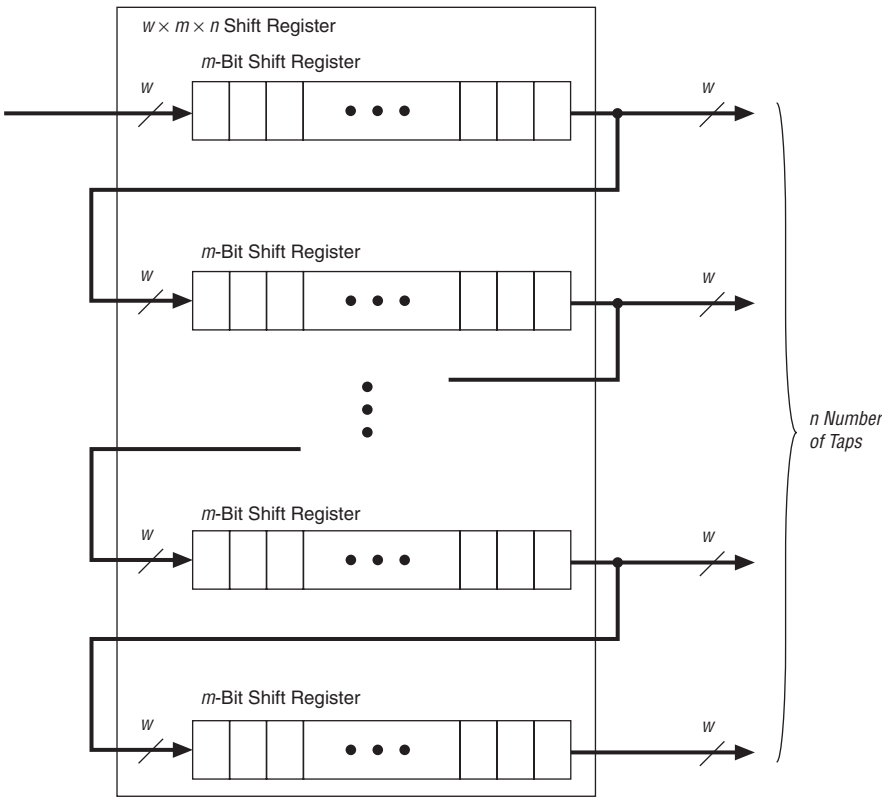
Table 1–4. Document Revision History

Date and Document Version	Changes Made	Summary of Changes
May 2008 v1.5	Minor textual and style changes.	—
January 2007 v1.4	Added document revision history.	—
August 2005 v1.3	Minor updates.	—
October 2003 v1.2	Added 64-bit PCI support information.	—
September 2003 v1.1	• Updated LVDS data rates to 640 Mbps from 311 Mbps. • Updated RSDS feature information.	—
May 2003 v1.0	Added document to Cyclone Device Handbook.	—

register outputs (number of taps n × width w) must be less than the maximum data width of the M4K RAM block (×36). To create larger shift registers, multiple memory blocks are cascaded together.

Data is written into each address location at the falling edge of the clock and read from the address at the rising edge of the clock. The shift register mode logic automatically controls the positive and negative edge clocking to shift the data in one clock cycle. Figure 2–14 shows the M4K memory block in the shift register mode.

Figure 2–14. Shift Register Memory Configuration



Memory Configuration Sizes

The memory address depths and output widths can be configured as 4,096 × 1, 2,048 × 2, 1,024 × 4, 512 × 8 (or 512 × 9 bits), 256 × 16 (or 256 × 18 bits), and 128 × 32 (or 128 × 36 bits). The 128 × 32- or 36-bit configuration

Byte Enables

M4K blocks support byte writes when the write port has a data width of 16, 18, 32, or 36 bits. The byte enables allow the input data to be masked so the device can write to specific bytes. The unwritten bytes retain the previous written value. Table 2–5 summarizes the byte selection.

Table 2–5. Byte Enable for M4K Blocks *Notes (1), (2)*

byteena[3..0]	datain ×18	datain ×36
[0] = 1	[8..0]	[8..0]
[1] = 1	[17..9]	[17..9]
[2] = 1	—	[26..18]
[3] = 1	—	[35..27]

Notes to Table 2–5:
(1) Any combination of byte enables is possible.
(2) Byte enables can be used in the same manner with 8-bit words, i.e., in ×16 and ×32 modes.

Control Signals and M4K Interface

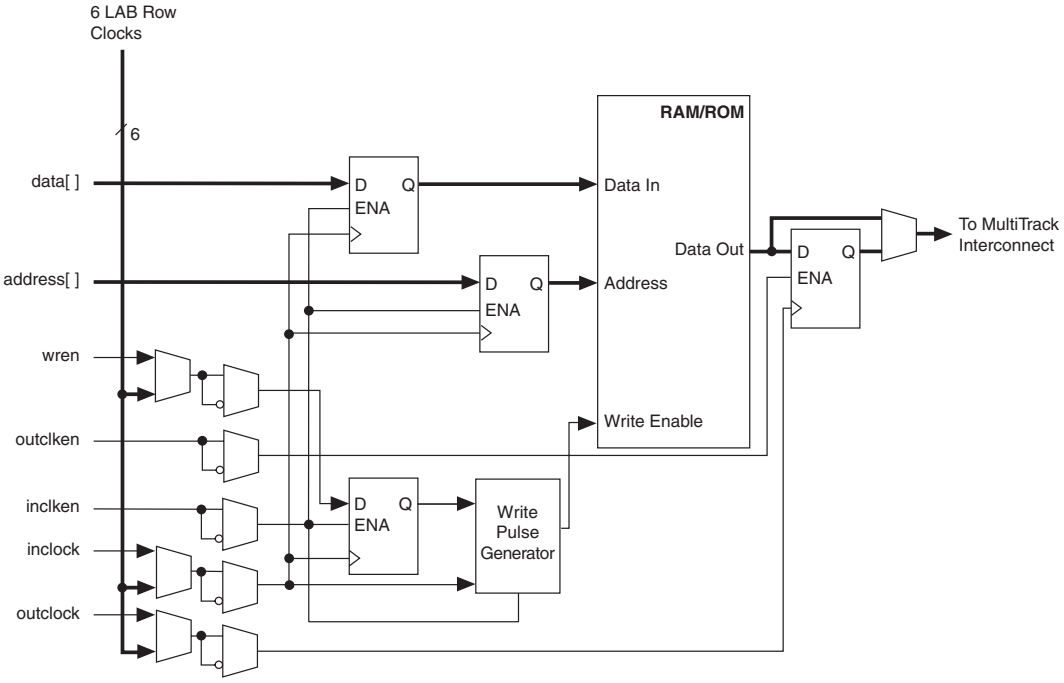
The M4K blocks allow for different clocks on their inputs and outputs. Either of the two clocks feeding the block can clock M4K block registers (`renwe`, address, byte enable, `datain`, and output registers). Only the output register can be bypassed. The six `labclk` signals or local interconnects can drive the control signals for the A and B ports of the M4K block. LEs can also control the `clock_a`, `clock_b`, `renwe_a`, `renwe_b`, `clr_a`, `clr_b`, `clocken_a`, and `clocken_b` signals, as shown in Figure 2–15.

The R4, C4, and direct link interconnects from adjacent LABs drive the M4K block local interconnect. The M4K blocks can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 10 direct link input connections to the M4K block are possible from the left adjacent LABs and another 10 possible from the right adjacent LAB. M4K block outputs can also connect to left and right LABs through 10 direct link interconnects each. Figure 2–16 shows the M4K block to logic array interface.

Single-Port Mode

The M4K memory blocks also support single-port mode, used when simultaneous reads and writes are not required. See Figure 2–21. A single M4K memory block can support up to two single-port mode RAM blocks if each RAM block is less than or equal to 2K bits in size.

Figure 2–21. Single-Port Mode *Note (1)*



Note to Figure 2–21:

(1) Violating the setup or hold time on the address registers could corrupt the memory contents. This applies to both read and write operations.

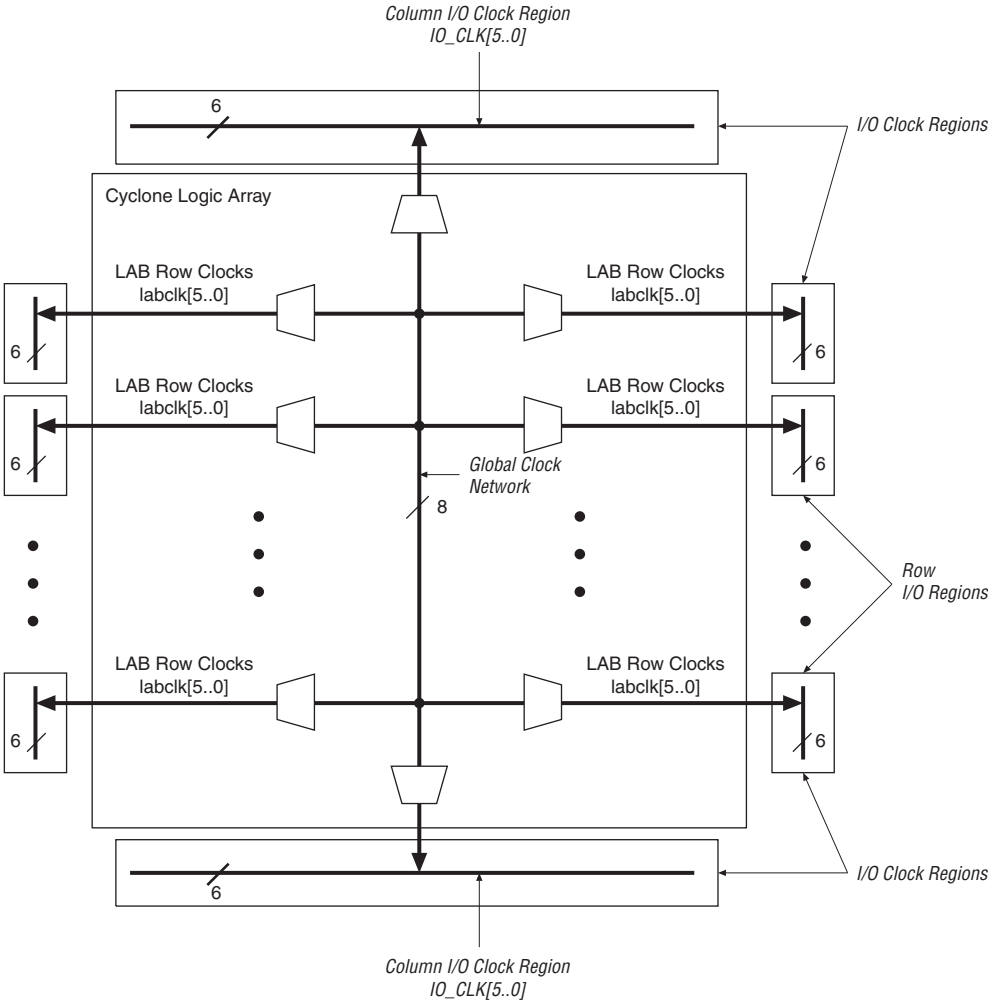
Global Clock Network and Phase-Locked Loops

Cyclone devices provide a global clock network and up to two PLLs for a complete clock management solution.

Global Clock Network

There are four dedicated clock pins (`CLK[3..0]`, two pins on the left side and two pins on the right side) that drive the global clock network, as shown in Figure 2–22. PLL outputs, logic array, and dual-purpose clock (`DPCLK[7..0]`) pins can also drive the global clock network.

Figure 2–24. I/O Clock Regions



PLLs

Cyclone PLLs provide general-purpose clocking with clock multiplication and phase shifting as well as outputs for differential I/O support. Cyclone devices contain two PLLs, except for the EP1C3 device, which contains one PLL.

Programmable Duty Cycle

The programmable duty cycle allows PLLs to generate clock outputs with a variable duty cycle. This feature is supported on each PLL post-scale counter (g0, g1, e). The duty cycle setting is achieved by a low- and high-time count setting for the post-scale dividers. The Quartus II software uses the frequency input and the required multiply or divide rate to determine the duty cycle choices.

Control Signals

There are three control signals for clearing and enabling PLLs and their outputs. You can use these signals to control PLL resynchronization and the ability to gate PLL output clocks for low-power applications.

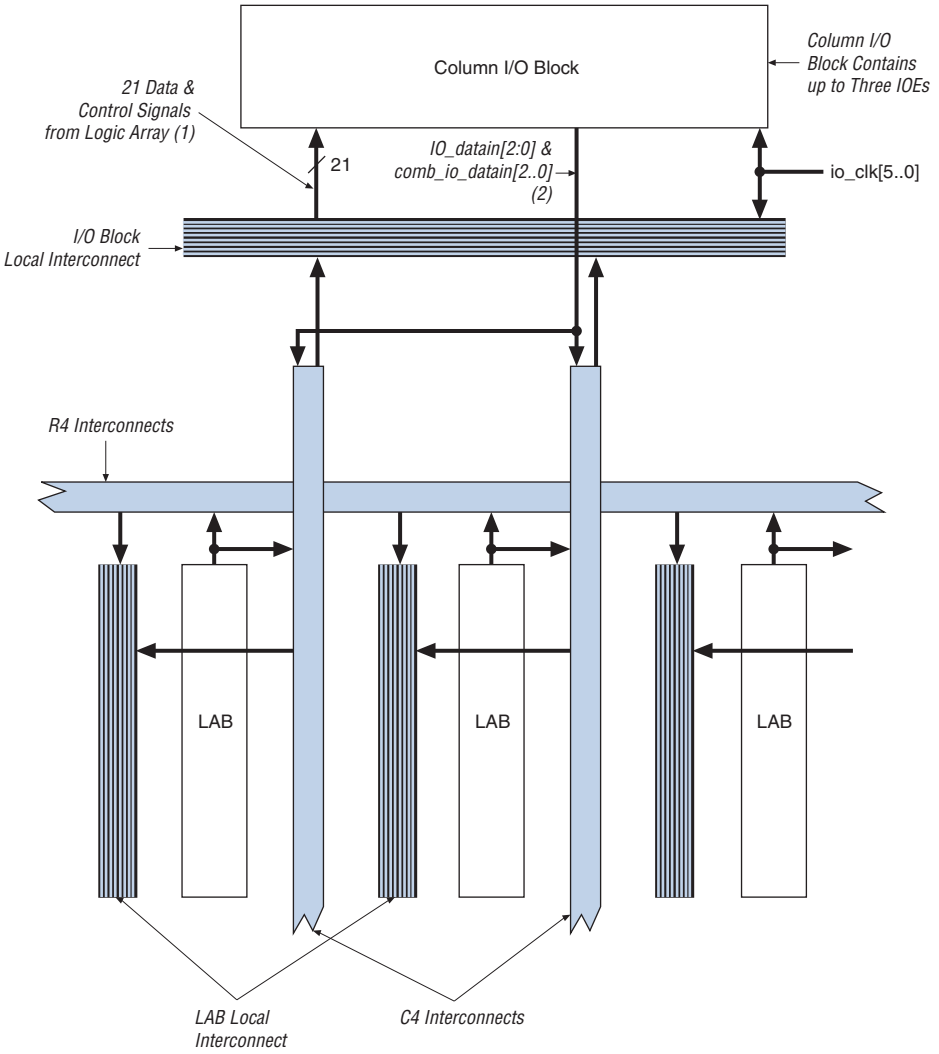
The `pllenable` signal enables and disables PLLs. When the `pllenable` signal is low, the clock output ports are driven by ground and all the PLLs go out of lock. When the `pllenable` signal goes high again, the PLLs relock and resynchronize to the input clocks. An input pin or LE output can drive the `pllenable` signal.

The `areset` signals are reset/resynchronization inputs for each PLL. Cyclone devices can drive these input signals from input pins or from LEs. When `areset` is driven high, the PLL counters will reset, clearing the PLL output and placing the PLL out of lock. When driven low again, the PLL will resynchronize to its input as it relocks.

The `pfdena` signals control the phase frequency detector (PFD) output with a programmable gate. If you disable the PFD, the VCO will operate at its last set value of control voltage and frequency with some drift, and the system will continue running when the PLL goes out of lock or the input clock disables. By maintaining the last locked frequency, the system has time to store its current settings before shutting down. You can either use their own control signal or gated locked status signals to trigger the `pfdena` signal.

For more information about Cyclone PLLs, refer to *Using PLLs in Cyclone Devices* chapter in the *Cyclone Device Handbook*.

Figure 2–29. Column I/O Block Connection to the Interconnect

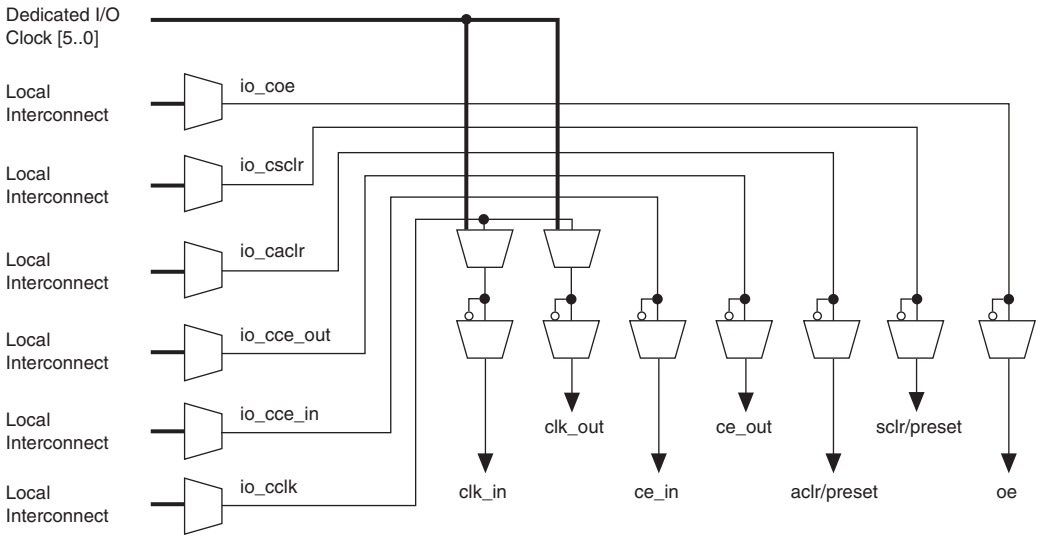


Notes to Figure 2–29:

(1) The 21 data and control signals consist of three data out lines, `io_dataout[2..0]`, three output enables, `io_coe[2..0]`, three input clock enables, `io_cce_in[2..0]`, three output clock enables, `io_cce_out[2..0]`, three clocks, `io_cclk[2..0]`, three asynchronous clear signals, `io_caclr[2..0]`, and three synchronous clear signals, `io_csclr[2..0]`.

(2) Each of the three IOEs in the column I/O block can have one `io_datain` input (combinatorial or registered) and one `comb_io_datain` (combinatorial) input.

Figure 2–31. Control Signal Selection per IOE



In normal bidirectional operation, you can use the input register for input data requiring fast setup times. The input register can have its own clock input and clock enable separate from the OE and output registers. The output register can be used for data requiring fast clock-to-output performance. The OE register is available for fast clock-to-output enable timing. The OE and output register share the same clock source and the same clock enable source from the local interconnect in the associated LAB, dedicated I/O clocks, or the column and row interconnects. Figure 2–32 shows the IOE in bidirectional configuration.

Advanced I/O Standard Support

Cyclone device IOEs support the following I/O standards:

- 3.3-V LVTTL/LVCMOS
- 2.5-V LVTTL/LVCMOS
- 1.8-V LVTTL/LVCMOS
- 1.5-V LVCMOS
- 3.3-V PCI
- LVDS
- RSDS
- SSTL-2 class I and II
- SSTL-3 class I and II
- Differential SSTL-2 class II (on output clocks only)

Table 2–12 describes the I/O standards supported by Cyclone devices.

Table 2–12. Cyclone I/O Standards

I/O Standard	Type	Input Reference Voltage (V_{REF}) (V)	Output Supply Voltage (V_{CCIO}) (V)	Board Termination Voltage (V_{TT}) (V)
3.3-V LVTTL/LVCMOS	Single-ended	N/A	3.3	N/A
2.5-V LVTTL/LVCMOS	Single-ended	N/A	2.5	N/A
1.8-V LVTTL/LVCMOS	Single-ended	N/A	1.8	N/A
1.5-V LVCMOS	Single-ended	N/A	1.5	N/A
3.3-V PCI *(1)*	Single-ended	N/A	3.3	N/A
LVDS *(2)*	Differential	N/A	2.5	N/A
RSDS *(2)*	Differential	N/A	2.5	N/A
SSTL-2 class I and II	Voltage-referenced	1.25	2.5	1.25
SSTL-3 class I and II	Voltage-referenced	1.5	3.3	1.5
Differential SSTL-2 *(3)*	Differential	1.25	2.5	1.25

Notes to Table 2–12:

(1) There is no megafunction support for EP1C3 devices for the PCI compiler. However, EP1C3 devices support PCI by using the LVTTL 16-mA I/O standard and drive strength assignments in the Quartus II software. The device requires an external diode for PCI compliance.

(2) EP1C3 devices in the 100-pin TQFP package do not support the LVDS and RSDS I/O standards.

(3) This I/O standard is only available on output clock pins (`PLL_OUT` pins). EP1C3 devices in the 100-pin package do not support this I/O standard as it does not have `PLL_OUT` pins.

Cyclone devices contain four I/O banks, as shown in Figure 2–35. I/O banks 1 and 3 support all the I/O standards listed in Table 2–12. I/O banks 2 and 4 support all the I/O standards listed in Table 2–12 except the 3.3-V PCI standard. I/O banks 2 and 4 contain dual-purpose DQS, DQ,

The Cyclone device instruction register length is 10 bits and the USERCODE register length is 32 bits. Tables 3–2 and 3–3 show the boundary-scan register length and device IDCODE information for Cyclone devices.

Table 3–2. Cyclone Boundary-Scan Register Length

Device	Boundary-Scan Register Length
EP1C3	339
EP1C4	930
EP1C6	582
EP1C12	774
EP1C20	930

Table 3–3. 32-Bit Cyclone Device IDCODE

Device	IDCODE (32 bits) *(1)*			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer Identity (11 Bits)	LSB (1 Bit) *(2)*
EP1C3	0000	0010 0000 1000 0001	000 0110 1110	1
EP1C4	0000	0010 0000 1000 0101	000 0110 1110	1
EP1C6	0000	0010 0000 1000 0010	000 0110 1110	1
EP1C12	0000	0010 0000 1000 0011	000 0110 1110	1
EP1C20	0000	0010 0000 1000 0100	000 0110 1110	1

Notes to Table 3–3:

(1) The most significant bit (MSB) is on the left.

(2) The IDCODE's least significant bit (LSB) is always 1.

Cyclone devices must be within the first 8 devices in a JTAG chain. All of these devices have the same JTAG controller. If any of the Cyclone devices are in the 9th or after they will fail configuration. This does not affect the SignalTap® II logic analyzer.

For more information on JTAG, refer to the following documents:

- *AN 39: IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices*
- *Jam Programming & Test Language Specification*

SignalTap II Embedded Logic Analyzer

Cyclone devices feature the SignalTap II embedded logic analyzer, which monitors design operation over a period of time through the IEEE Std. 1149.1 (JTAG) circuitry. A designer can analyze internal logic at speed without bringing internal signals to the I/O pins. This feature is particularly important for advanced packages, such as FineLine BGA packages, because it can be difficult to add a connection to a pin during the debugging process after a board is designed and manufactured.

Configuration

The logic, circuitry, and interconnects in the Cyclone architecture are configured with CMOS SRAM elements. Altera FPGAs are reconfigurable and every device is tested with a high coverage production test program so the designer does not have to perform fault testing and can instead focus on simulation and design verification.

Cyclone devices are configured at system power-up with data stored in an Altera configuration device or provided by a system controller. The Cyclone device's optimized interface allows the device to act as controller in an active serial configuration scheme with the new low-cost serial configuration device. Cyclone devices can be configured in under 120 ms using serial data at 20 MHz. The serial configuration device can be programmed via the ByteBlaster II download cable, the Altera Programming Unit (APU), or third-party programmers.

In addition to the new low-cost serial configuration device, Altera offers in-system programmability (ISP)-capable configuration devices that can configure Cyclone devices via a serial data stream. The interface also enables microprocessors to treat Cyclone devices as memory and configure them by writing to a virtual memory location, making reconfiguration easy. After a Cyclone device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

Table 4–5. LVCMOS Specifications

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCIO}	Output supply voltage	—	3.0	3.6	V
V_{IH}	High-level input voltage	—	1.7	4.1	V
V_{IL}	Low-level input voltage	—	–0.5	0.7	V
V_{OH}	High-level output voltage	V_{CCIO} = 3.0, I_{OH} = –0.1 mA	V_{CCIO} – 0.2	—	V
V_{OL}	Low-level output voltage	V_{CCIO} = 3.0, I_{OL} = 0.1 mA	—	0.2	V

Table 4–6. 2.5-V I/O Specifications

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCIO}	Output supply voltage	—	2.375	2.625	V
V_{IH}	High-level input voltage	—	1.7	4.1	V
V_{IL}	Low-level input voltage	—	–0.5	0.7	V
V_{OH}	High-level output voltage	I_{OH} = –0.1 mA	2.1	—	V
		I_{OH} = –1 mA	2.0	—	V
		I_{OH} = –2 to –16 mA *(11)*	1.7	—	V
V_{OL}	Low-level output voltage	I_{OL} = 0.1 mA	—	0.2	V
		I_{OH} = 1 mA	—	0.4	V
		I_{OH} = 2 to 16 mA *(11)*	—	0.7	V

Table 4–7. 1.8-V I/O Specifications

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCIO}	Output supply voltage	—	1.65	1.95	V
V_{IH}	High-level input voltage	—	0.65 × V_{CCIO}	2.25 *(12)*	V
V_{IL}	Low-level input voltage	—	–0.3	0.35 × V_{CCIO}	V
V_{OH}	High-level output voltage	I_{OH} = –2 to –8 mA *(11)*	V_{CCIO} – 0.45	—	V
V_{OL}	Low-level output voltage	I_{OL} = 2 to 8 mA *(11)*	—	0.45	V

Table 4–24. Routing Delay Internal Timing Microparameter Descriptions	
Symbol	**Parameter**
t_{R4}	Delay for an R4 line with average loading; covers a distance of four LAB columns
t_{C4}	Delay for an C4 line with average loading; covers a distance of four LAB rows
t_{LOCAL}	Local interconnect delay

Figure 4–1 shows the memory waveforms for the M4K timing parameters shown in Table 4–23.

Figure 4–1. Dual-Port RAM Timing Microparameter Waveform

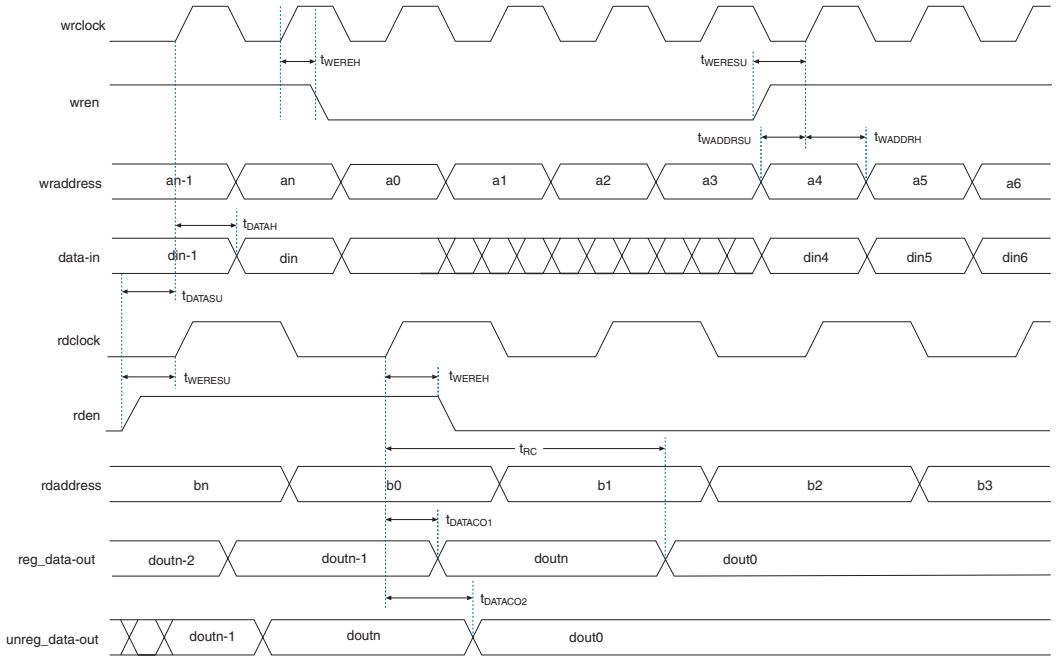


Table 4–27. M4K Block Internal Timing Microparameters

Symbol	-6		-7		-8		Unit
	Min	Max	Min	Max	Min	Max	
t_{M4KRC}	—	4,379		5,035		5,691	ps
t_{M4KWC}	—	2,910		3,346		3,783	ps
$t_{M4KWERESU}$	72	—	82	—	93	—	ps
$t_{M4KWEREH}$	43	—	49	—	55	—	ps
$t_{M4KBESU}$	72	—	82	—	93	—	ps
t_{M4KBEH}	43	—	49	—	55	—	ps
$t_{M4KDATAASU}$	72	—	82	—	93	—	ps
$t_{M4KDATAAH}$	43	—	49	—	55	—	ps
$t_{M4KADDRASU}$	72	—	82	—	93	—	ps
$t_{M4KADDRAH}$	43	—	49	—	55	—	ps
$t_{M4KDATABSU}$	72	—	82	—	93	—	ps
$t_{M4KDATABH}$	43	—	49	—	55	—	ps
$t_{M4KADDRBSU}$	72	—	82	—	93	—	ps
$t_{M4KADDRBH}$	43	—	49	—	55	—	ps
$t_{M4KDATACO1}$	—	621	—	714	—	807	ps
$t_{M4KDATACO2}$	—	4,351	—	5,003	—	5,656	ps
$t_{M4KCLKHL}$	1,234	—	1,562	—	1,818	—	ps
t_{M4KCLR}	286	—	328	—	371	—	ps

Table 4–28. Routing Delay Internal Timing Microparameters

Symbol	-6		-7		-8		Unit
	Min	Max	Min	Max	Min	Max	
t_{R4}	—	261	—	300	—	339	ps
t_{C4}	—	338	—	388	—	439	ps
t_{LOCAL}	—	244	—	281	—	318	ps

External Timing Parameters

External timing parameters are specified by device density and speed grade. Figure 4–2 shows the timing model for bidirectional IOE pin timing. All registers are within the IOE.

Tables 4–32 through 4–33 show the external timing parameters on column and row pins for EP1C4 devices.

Table 4–32. EP1C4 Column Pin Global Clock External I/O Timing Parameters *Note (1)*

Symbol	-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.471	—	2.841	—	3.210	—	ns
t_{INH}	0.000	—	0.000	—	0.000	—	ns
t_{OUTCO}	2.000	3.937	2.000	4.526	2.000	5.119	ns
$t_{INSUPLL}$	1.471	—	1.690	—	1.910	—	ns
t_{INHPLL}	0.000	—	0.000	—	0.000	—	ns
$t_{OUTCOPLL}$	0.500	2.080	0.500	2.392	0.500	2.705	ns

Table 4–33. EP1C4 Row Pin Global Clock External I/O Timing Parameters *Note (1)*

Symbol	-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.600	—	2.990	—	3.379	—	ns
t_{INH}	0.000	—	0.000	—	0.000	—	ns
t_{OUTCO}	2.000	3.991	2.000	4.388	2.000	5.189	ns
$t_{INSUPLL}$	1.300	—	1.494	—	1.689	—	ns
t_{INHPLL}	0.000	—	0.000	—	0.000	—	ns
$t_{OUTCOPLL}$	0.500	2.234	0.500	2.569	0.500	2.905	ns

Note to Tables 4–32 and 4–33:
(1) Contact Altera Applications for EP1C4 device timing parameters.

Table 4–39. EP1C20 Row Pin Global Clock External I/O Timing Parameters							
Symbol	-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.417	—	2.779	—	3.140	—	ns
t_{INH}	0.000	—	0.000	—	0.000	—	ns
t_{OUTCO}	2.000	3.724	2.000	4.282	2.000	4.843	ns
t_{XZ}	—	3.645	—	4.191	—	4.740	ns
t_{ZX}	—	3.645	—	4.191	—	4.740	ns
$t_{INSUPLL}$	1.417	—	1.629	—	1.840	—	ns
t_{INHPLL}	0.000	—	0.000	—	0.000	—	ns
$t_{OUTCOPLL}$	0.500	1.667	0.500	1.917	0.500	2.169	ns
t_{XZPLL}	—	1.588	—	1.826	—	2.066	ns
t_{ZXPLL}	—	1.588	—	1.826	—	2.066	ns

External I/O Delay Parameters

External I/O delay timing parameters for I/O standard input and output adders and programmable input and output delays are specified by speed grade independent of device density.

Tables 4–40 through 4–45 show the adder delays associated with column and row I/O pins for all packages. If an I/O standard is selected other than LVTTL 4 mA with a fast slew rate, add the selected delay to the external t_{CO} and t_{SU} I/O parameters shown in Tables 4–25 through 4–28.

Table 4–40. Cyclone I/O Standard Column Pin Input Delay Adders (Part 1 of 2)							
I/O Standard	-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
LVCMOS	—	0	—	0	—	0	ps
3.3-V LVTTL	—	0	—	0	—	0	ps
2.5-V LVTTL	—	27	—	31	—	35	ps
1.8-V LVTTL	—	182	—	209	—	236	ps
1.5-V LVTTL	—	278	—	319	—	361	ps
SSTL-3 class I	—	–250	—	–288	—	–325	ps
SSTL-3 class II	—	–250	—	–288	—	–325	ps
SSTL-2 class I	—	–278	—	–320	—	–362	ps

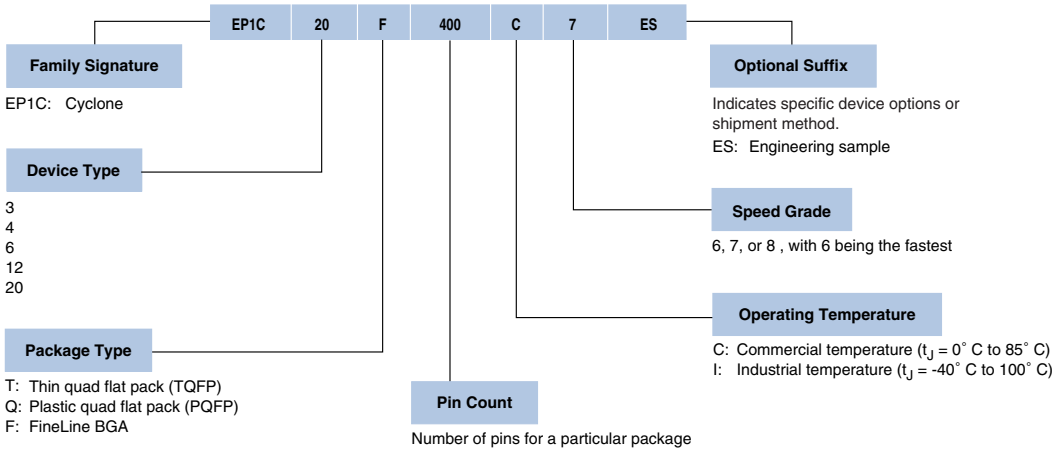
Table 4–44. Cyclone I/O Standard Output Delay Adders for Slow Slew Rate on Column Pins (Part 2 of 2)

I/O Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
1.5-V LVTTL	2 mA	—	6,789	—	7,807	—	8,825	ps
	4 mA	—	5,109	—	5,875	—	6,641	ps
	8 mA	—	4,793	—	5,511	—	6,230	ps
SSTL-3 class I		—	1,390	—	1,598	—	1,807	ps
SSTL-3 class II		—	989	—	1,137	—	1,285	ps
SSTL-2 class I		—	1,965	—	2,259	—	2,554	ps
SSTL-2 class II		—	1,692	—	1,945	—	2,199	ps
LVDS		—	802	—	922	—	1,042	ps

Table 4–45. Cyclone I/O Standard Output Delay Adders for Slow Slew Rate on Row Pins (Part 1 of 2)

I/O Standard		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
LVCMOS	2 mA	—	1,800	—	2,070	—	2,340	ps
	4 mA	—	1,311	—	1,507	—	1,704	ps
	8 mA	—	945	—	1,086	—	1,228	ps
	12 mA	—	807	—	928	—	1,049	ps
3.3-V LVTTL	4 mA	—	1,831	—	2,105	—	2,380	ps
	8 mA	—	1,484	—	1,705	—	1,928	ps
	12 mA	—	973	—	1,118	—	1,264	ps
	16 mA	—	1,012	—	1,163	—	1,315	ps
	24 mA	—	838	—	963	—	1,089	ps
2.5-V LVTTL	2 mA	—	2,747	—	3,158	—	3,570	ps
	8 mA	—	1,757	—	2,019	—	2,283	ps
	12 mA	—	1,763	—	2,026	—	2,291	ps
	16 mA	—	1,623	—	1,865	—	2,109	ps
1.8-V LVTTL	2 mA	—	5,506	—	6,331	—	7,157	ps
	8 mA	—	4,220	—	4,852	—	5,485	ps
	12 mA	—	4,008	—	4,608	—	5,209	ps
1.5-V LVTTL	2 mA	—	6,789	—	7,807	—	8,825	ps
	4 mA	—	5,109	—	5,875	—	6,641	ps
	8 mA	—	4,793	—	5,511	—	6,230	ps
3.3-V PCI		—	923	—	1,061	—	1,199	ps

Figure 5–1. Cyclone Device Packaging Ordering Information



Referenced Documents

This chapter references the following documents:

- *Package Information for Cyclone Devices* chapter in the *Cyclone Device Handbook*
- *Quartus II Handbook*

Document Revision History

Table 5–1 shows the revision history for this chapter.

Table 5–1. Document Revision History

Date and Document Version	Changes Made	Summary of Changes
May 2008 v1.4	Minor textual and style changes. Added "Referenced Documents" section.	—
January 2007 v1.3	Added document revision history.	—
August 2005 v1.2	Minor updates.	—